

13 12 11 10 9 8 7 6 5 4 3 2 1

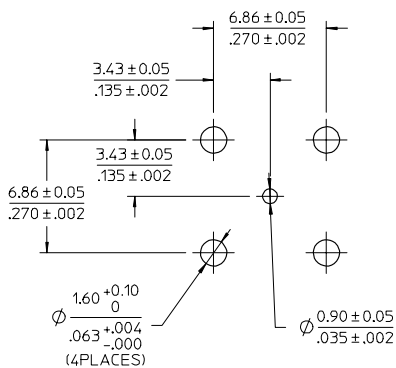
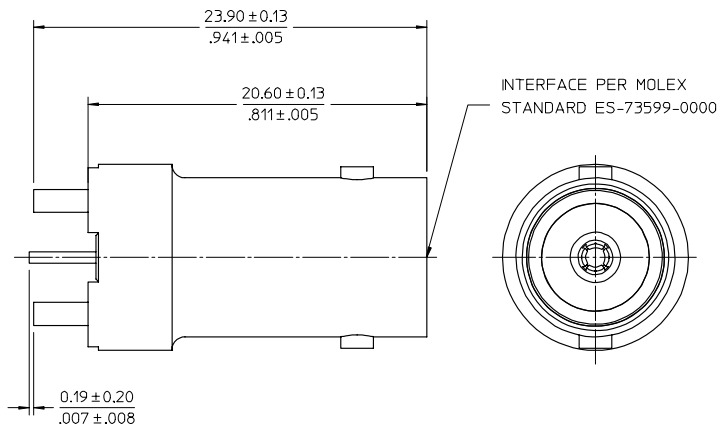
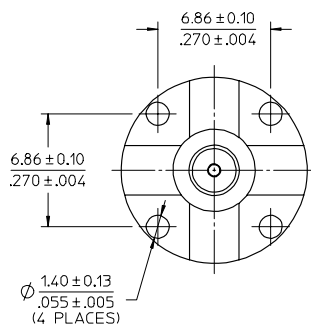
J
I
H
G
F
E
D
C
B
A

MATERIALS AND FINISHES

BODY ZINC ALLOY
PLATED NICKEL 70u" MIN

CENTER CONTACT
PHOSPHOR BRONZE
PLATED GOLD 30u" MIN

INSULATOR TEFLON



PCB HOLE CONFIGURATION

LOAD TO WM EC NO. URF-2008-0099 DRAWN/CLL I CHKD: 2007/08/17 APPR: HUANG REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		mm	INCH	MM/IN		METRIC	
		4 PLACES ±	±	DRAWN BY	DATE	TITLE	
		3 PLACES ±	±	CLL I	05/07/02	BNC JACK VERTICAL PCB	
		2 PLACES ±	±	CHECKED BY	DATE	75 OHM	
		1 PLACE ±	±	BETTY	05/07/02	BNC-J/PCB	
		ANGULAR ± 2 °		APPROVED BY	DATE	MOLEX INCORPORATED	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MISEN	05/07/02	MATERIAL NO.	DOCUMENT NO.
				73101-0360		73101-0360	SD-73101-036
				SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 1 OF 1

tb_frame_C_P_AM_T
Rev. E 2006/04/15

12 11 10 9 8 7 6 5 4 3 2 1

J
I
H
G
F
E
D
C
B
A